

2MBI200VA-060-50

IGBT Modules

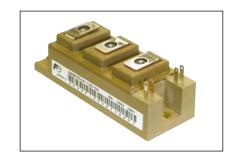
IGBT MODULE (V series) 600V / 200A / 2 in one package

■ Features

High speed switching Voltage drive Low Inductance module structure

Applications

Inverter for Motor Drive AC and DC Servo Drive Amplifier Uninterruptible Power Supply Industrial machines, such as Welding machines



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings (at T_c=25°C unless otherwise specified)

Items		Symbols Conditions			Maximum ratings	Units	
Collector-Emitter voltage		Vces		,	600	V	
Gate-Emitter voltage		V _{GES}			±20	V	
Collector current		Ic	Continuous	Tc=100°C	200		
		I _{C pulse}	1ms		400	٨	
		-Ic				Α	
		-I _{C pulse}	1ms	,	400		
Collector power dissipation		Pc	1 device		650		
Junction temperature		T _j			175		
Operating junction temperature (under switching conditions)		T _{jop}			150	°C	
Case temperature		Tc			125	C	
Storage temperature		T _{stg}		,	-40 ~ 125		
Isolation voltage	between terminal and copper base (*1)	Viso	AC: 1min.		2500	VAC	
Screw torque	Mounting (*2)	-			5.0	N m	
	Terminals (*3)	-			5.0	IN III	

Note *1: All terminals should be connected together when isolation test will be done.

Note *2: Recommendable Value : 3.0-5.0 Nm (M5 or M6) Note *3: Recommendable Value : 2.5-3.5 Nm (M5)

■ Electrical characteristics (at T_i= 25°C unless otherwise specified)

lama	Cumbala	Conditions		Characteristics			l lusita
Items	Symbols			min.	typ.	max.	Units
Zero gate voltage collector current	Ices	V _{GE} = 0V, V _{CE} = 600V		-	-	1.0	mA
Gate-Emitter leakage current	-Emitter leakage current I_{GES} $V_{CE} = 0V, V_{GE} = \pm 20V$		-	-	200	nA	
Gate-Emitter threshold voltage	V _{GE (th)}	$V_{CE} = 20V, I_{C} = 200mA$		6.2	6.7	7.2	V
	V _{CE (sat)}	V _{GE} = 15V I _C = 200A	T _j =25°C	-	1.80	2.25	V
	(terminal)		T _j =125°C	-	2.10	-	
Collector-Emitter saturation voltage			T _j =150°C		2.30		
Conector-Emitter Saturation Voltage	V _{CE (sat)} (chip)	V _{GE} = 15V I _C = 200A	T _j =25°C	-	1.60	2.05	
			T _j =125°C	-	1.90	-	
			T _j =150°C		2.10		
Internal gate resistance	R _G (int)	-			4	-	Ω
Input capacitance	Cies	$V_{CE} = 10V, V_{GE} = 0V, f = 1W$	-	12.8	-	nF	
	ton	$V_{\text{CC}} = 300V$		-	650	-	nsec
Turn-on time	tr			-	300	-	
	t r (i)			-	100	-	
Turn-off time	toff			-	600	-	
Turn-on time	t _f			-	40	-	
	VF	V _{GE} = 0V I _F = 200A	T _j =25°C	-	1.70	2.15	V
	(terminal)		T _j =125°C	-	1.60	-	
Forward on voltage	(terrillial)	IF - 200A	T _j =150°C		1.57		
rorward on voltage	VF	V _{GE} = 0V I _F = 200A	T _j =25°C	-	1.60	2.05	
			T _j =125°C	-	1.50	-	
	(chip)	IF - 200A	T _j =150°C		1.47		
everse recovery time t_{rr} $I_F = 200A$		-	200	-	nsec		

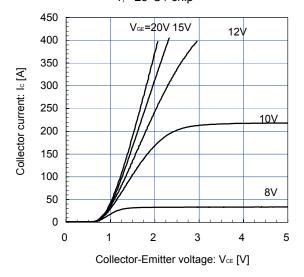
Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Units
items		Conditions	min.	typ.	max.	Units
Thermal resistance (Aderrica)	Ь	IGBT	-	-	0.23	°C/W
Thermal resistance (1device)	R _{th(j-c)}	FWD	-	-	0.41	
Contact thermal resistance (1device) (*4)	R _{th(c-f)}	with Thermal Compound	-	0.050	-	

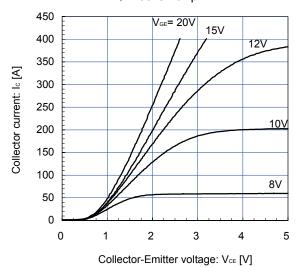
Note *4: This is the value which is defined mounting on the additional cooling fin with thermal compound.

■ Characteristics (Representative)

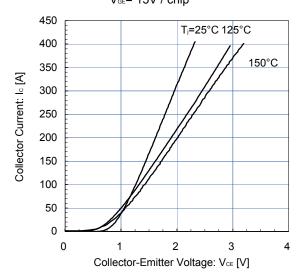
Collector current vs. Collector-Emitter voltage (typ.) $T_j = 25^{\circ}C$ / chip



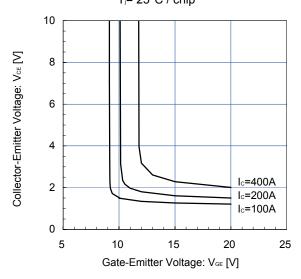
Collector current vs. Collector-Emitter voltage (typ.) T₌ 150°C / chip



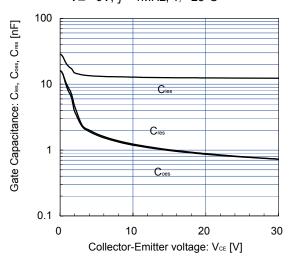
Collector current vs. Collector-Emitter voltage (typ.) V_{GE} = 15V / chip



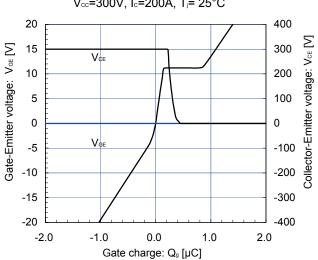
Collector-Emitter voltage vs. Gate-Emitter voltage T_j= 25°C / chip

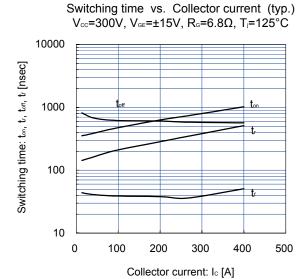


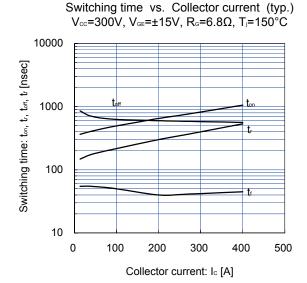
Gate Capacitance vs. Collector-Emitter Voltage V_{GE} = 0V, f= 1MHz, T_{J} = 25°C

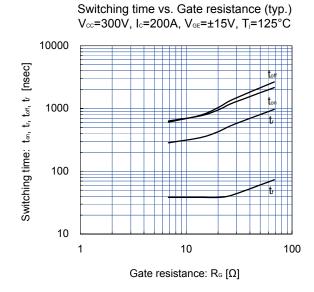


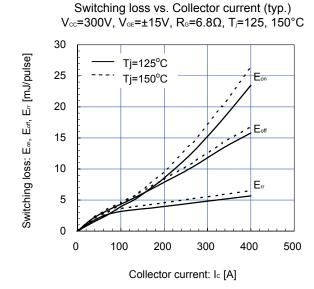
Dynamic Gate Charge (typ.) V_{cc}=300V, I_c=200A, T_i= 25°C

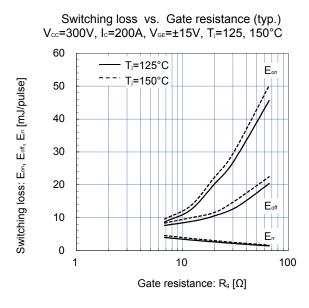


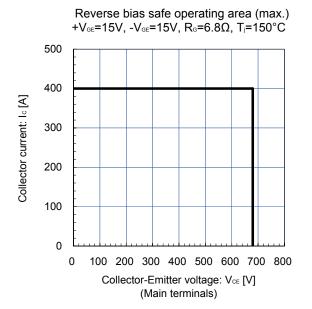




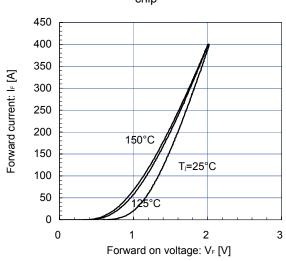




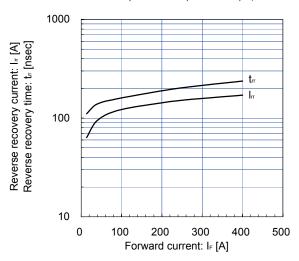




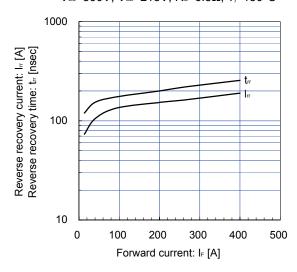
Forward Current vs. Forward Voltage (typ.) chip



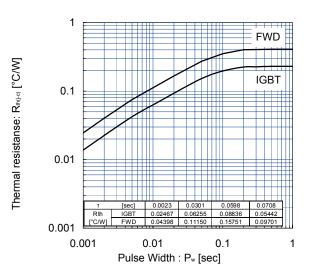
Reverse Recovery Characteristics (typ.) V_{CC} =300V, V_{GE} =±15V, R_{G} =6.8 Ω , T_{J} =125°C



Reverse Recovery Characteristics (typ.) V_{CC} =300V, V_{GE} =±15V, R_{G} =6.8 Ω , T_{J} =150°C

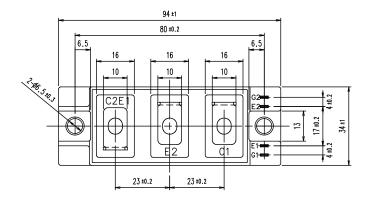


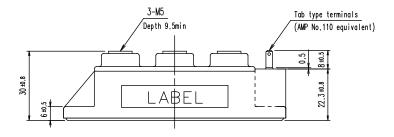
Transient Thermal Resistance (max.)



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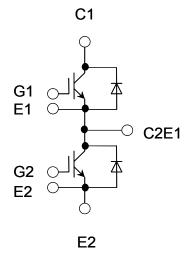
■ Outline Drawings, mm





Weight: 180g (typ.)

■ Equivalent Circuit Schematic



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